



## Description

### JMP N-channel Enhancement Mode Power MOSFET

#### Features

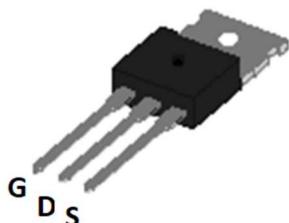
- 650V, 7A
- $R_{DS(ON)} < 1.35\Omega$  @  $V_{GS} = 10V$
- Fast Switching
- Improved dv/dt Capability

#### Application

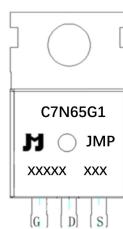
- Load Switch
- PWM Application
- Power management



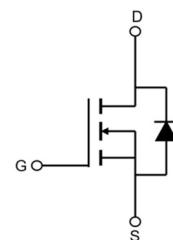
100% UIS TESTED!  
100%  $\Delta V_{ds}$  TESTED!



TO-220C top view



Marking and pin Assignment



Schematic Diagram

## Package Marking and Ordering Information

Device Marking	Device	OUTLINE	Device Package	TUBE (PCS)	Inner Box (PCS)	Per Carton (PCS)
JMPC7N65G1	JMPC7N65G1	TUBE	TO-220C	50	1,000	5,000

## Absolute Maximum Ratings ( $T_c=25^\circ C$ unless otherwise specified)

Symbol	Parameter		Max.	Units
$V_{DSS}$	Drain-Source Voltage		650	V
$V_{GSS}$	Gate-Source Voltage		$\pm 30$	V
$I_D$	Continuous Drain Current	$T_c = 25^\circ C$	7	A
		$T_c = 100^\circ C$	4.5	A
$I_{DM}$	Pulsed Drain Current <sup>note1</sup>		28	A
$E_{AS}$	Single Pulsed Avalanche Energy <sup>note2</sup>		198	mJ
$P_D$	Power Dissipation	$T_c = 25^\circ C$	63	W
$R_{θJC}$	Thermal Resistance, Junction to Case		1.98	$^\circ C / W$
$R_{θJA}$	Thermal Resistance, Junction to Ambient		62.5	$^\circ C / W$
$T_J, T_{STG}$	Operating and Storage Temperature Range		-55 to +150	$^\circ C$

**Electrical Characteristics** ( $T_J=25^\circ\text{C}$  unless otherwise specified)

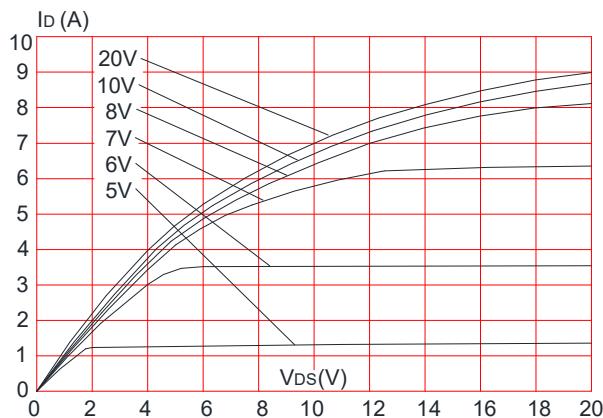
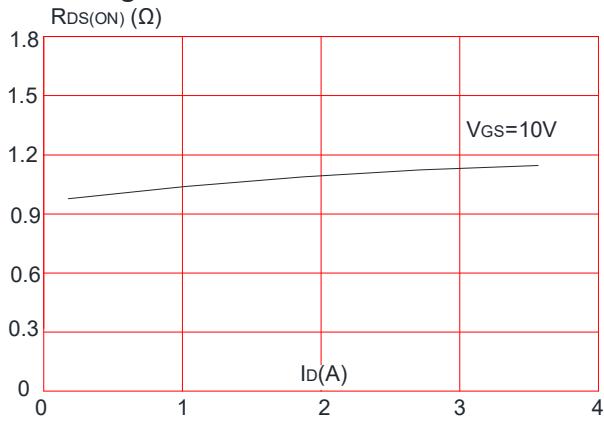
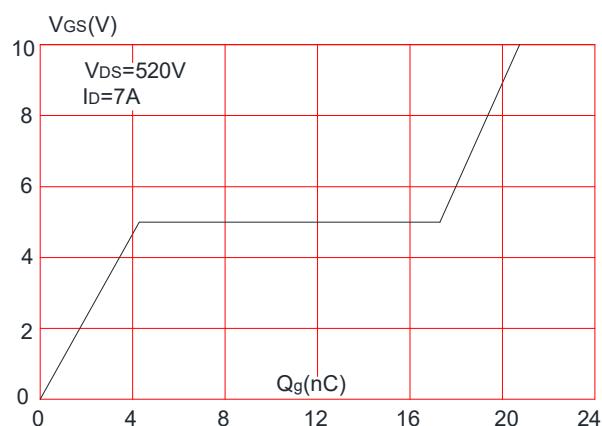
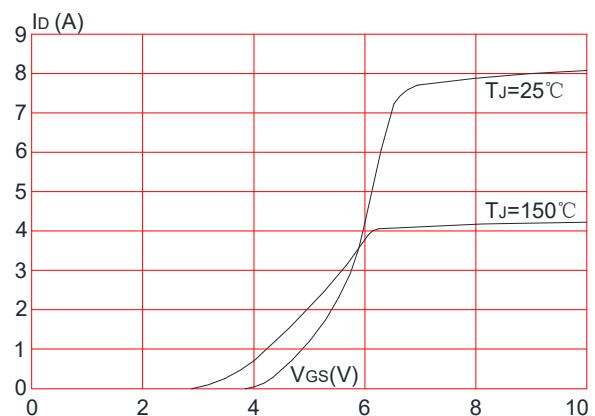
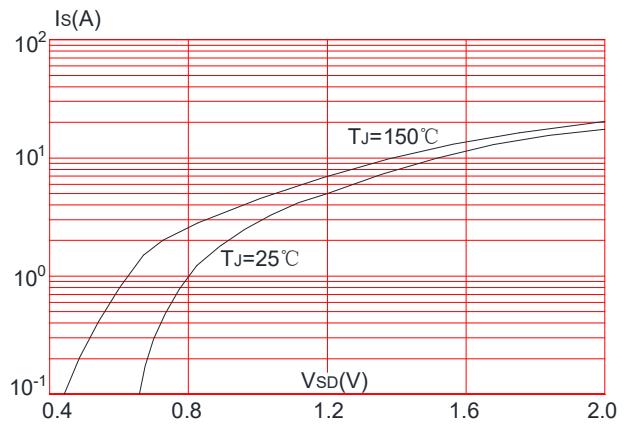
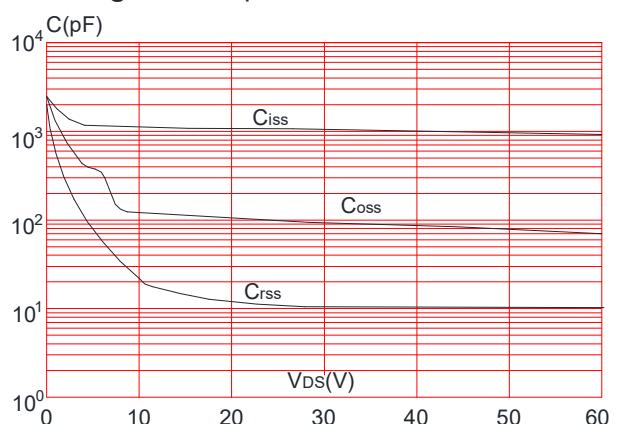
Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
<b>Off Characteristic</b>						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{GS} = 0\text{V}, I_D = 250\mu\text{A}$	650	-	-	V
$I_{\text{DSS}}$	Zero Gate Voltage Drain Current	$V_{DS} = 650\text{V}, V_{GS} = 0\text{V}, T_J = 25^\circ\text{C}$	-	-	1	$\mu\text{A}$
$I_{\text{GSS}}$	Gate to Body Leakage Current	$V_{GS} = \pm 30\text{V}$	-	-	$\pm 100$	nA
<b>On Characteristics</b>						
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	2	-	4	V
$R_{\text{DS(on)}}$	Static Drain-Source On-Resistance note3	$V_{GS} = 10\text{V}, I_D = 3.5\text{A}$	-	1.15	1.35	$\Omega$
<b>Dynamic Characteristics</b>						
$C_{\text{iss}}$	Input Capacitance	$V_{DS} = 25\text{V}, V_{GS} = 0\text{V}, f = 1.0\text{MHz}$	-	1148	-	pF
$C_{\text{oss}}$	Output Capacitance		-	106	-	pF
$C_{\text{rss}}$	Reverse Transfer Capacitance		-	12	-	pF
$Q_g$	Total Gate Charge	$V_{DS} = 520\text{V}, I_D = 7\text{A}, V_{GS} = 10\text{V}$	-	22	-	nC
$Q_{gs}$	Gate-Source Charge		-	4.3	-	nC
$Q_{gd}$	Gate-Drain("Miller") Charge		-	13	-	nC
<b>Switching Characteristics</b>						
$t_{d(\text{on})}$	Turn-On Delay Time	$V_{DD} = 325\text{V}, I_D = 7\text{A}, R_G = 25\Omega$	-	15	-	ns
$t_r$	Turn-On Rise Time		-	18	-	ns
$t_{d(\text{off})}$	Turn-Off Delay Time		-	80	-	ns
$t_f$	Turn-Off Fall Time		-	35	-	ns
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
$I_S$	Maximum Continuous Drain to Source Diode Forward Current	-	-	7	A	
$I_{SM}$	Maximum Pulsed Drain to Source Diode Forward Current	-	-	28	A	
$V_{SD}$	Drain to Source Diode Forward Voltage	$V_{GS} = 0\text{V}, I_{SD} = 7\text{A}, T_J = 25^\circ\text{C}$	-	-	1.4	V
$t_{rr}$	Reverse Recovery Time	$V_{GS} = 0\text{V}, I_S = 7\text{A}, \frac{di}{dt} = 100\text{A}/\mu\text{s}$	-	300	-	ns
$Q_{rr}$	Reverse Recovery Charge		-	4.1	-	$\mu\text{C}$

Notes: 1. Repetitive Rating: Pulse width limited by maximum junction temperature

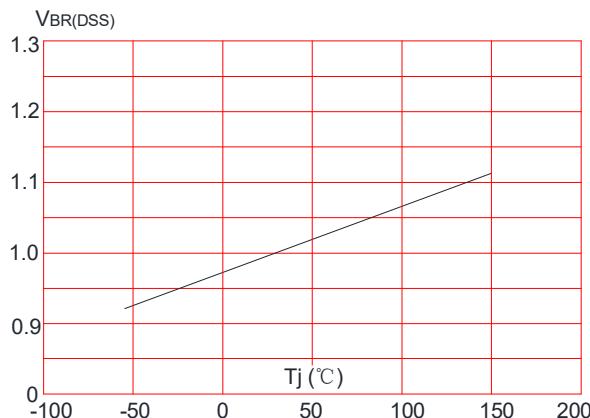
2. EAS condition:  $T_J = 25^\circ\text{C}, V_{DD} = 50\text{V}, V_G = 10\text{V}, L = 10\text{mH}, I_{AS} = 6.3\text{A}$

3. Pulse Test: Pulse width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 1\%$

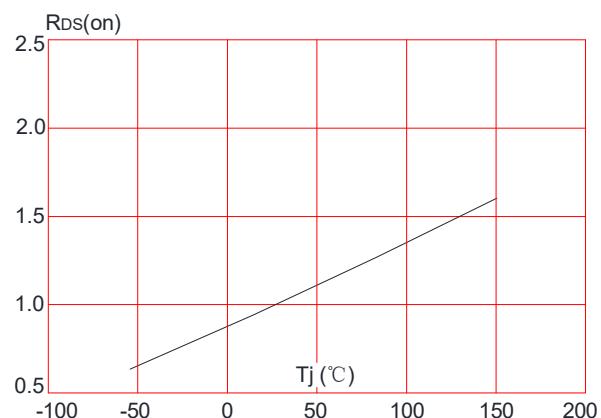
**Typical Performance Characteristics**

**Figure1:** Output Characteristics

**Figure 3:** On-resistance vs. Drain Current

**Figure 5:** Gate Charge Characteristics

**Figure 2:** Typical Transfer Characteristics

**Figure 4:** Body Diode Characteristics

**Figure 6:** Capacitance Characteristics


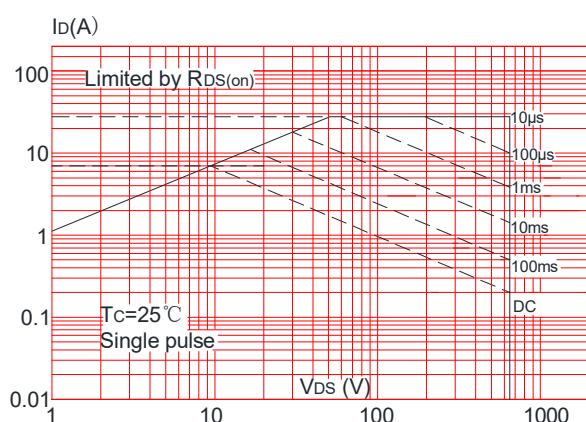
**Figure 7:** Normalized Breakdown Voltage vs. Junction Temperature



**Figure 8:** Normalized on Resistance vs. Junction Temperature

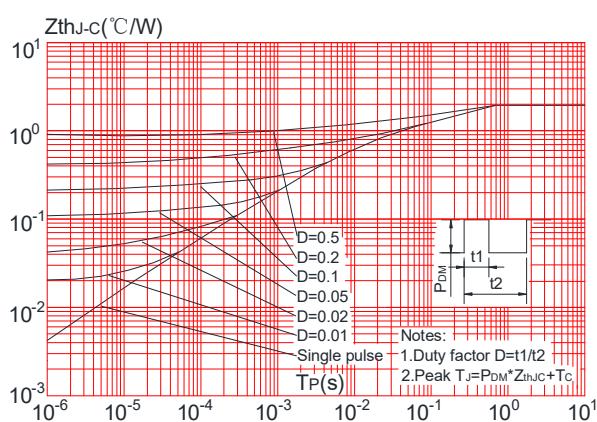
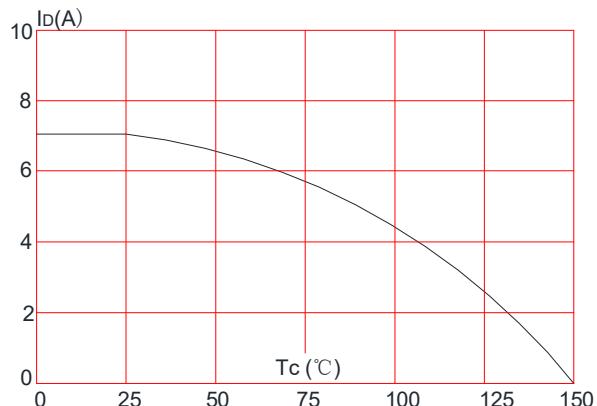


**Figure 9:** Maximum Safe Operating Area

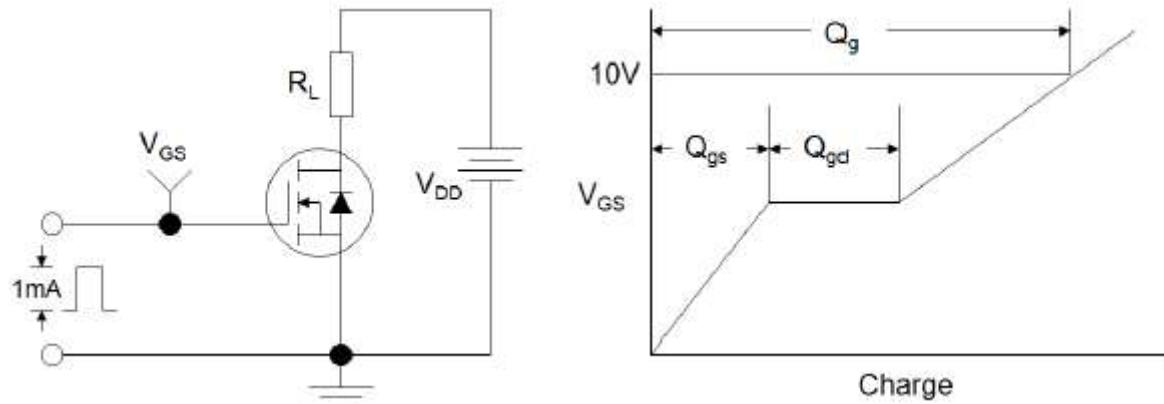


**Figure 11:** Maximum Effective Transient Thermal Impedance, Junction-to-Case

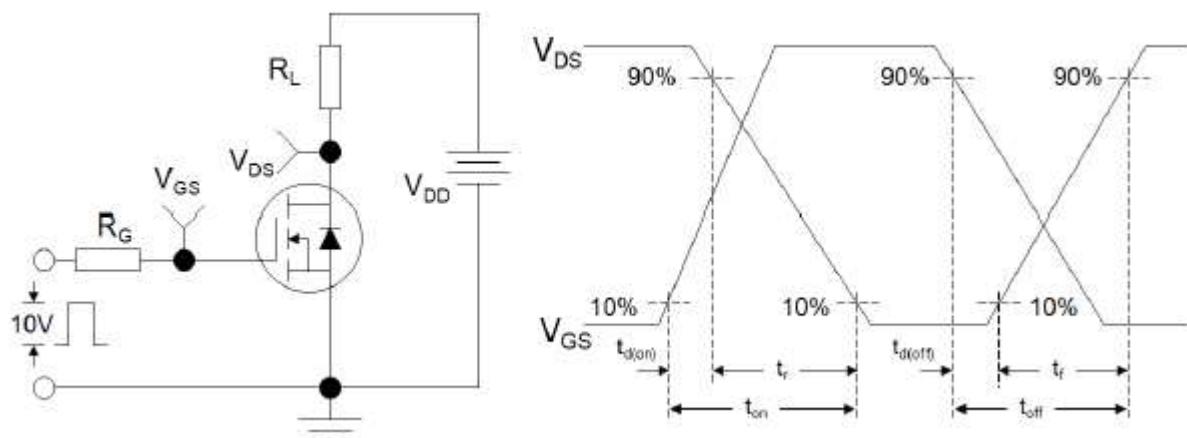
**Figure 10:** Maximum Continuous Drain Current vs. Case Temperature



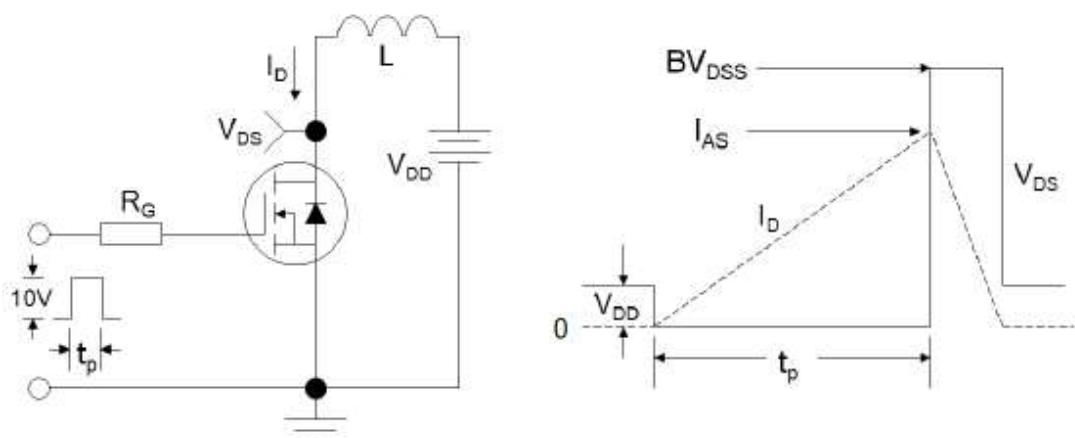
## Test Circuit



**Figure1:Gate Charge Test Circuit & Waveform**



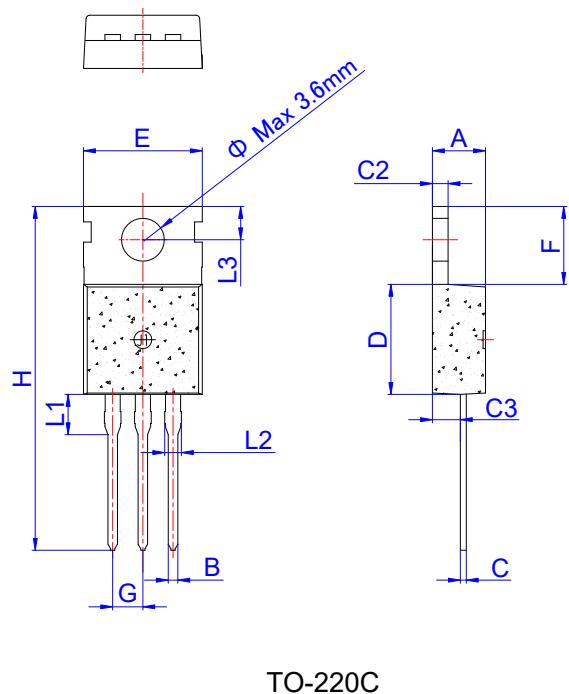
**Figure 2: Resistive Switching Test Circuit & Waveforms**



**Figure 3:Unclamped Inductive Switching Test Circuit & Waveforms**



## Package Mechanical Data- TO-220C



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	4.40		4.60	0.173		0.181
B	0.70		0.90	0.028		0.035
C	0.45		0.60	0.018		0.024
C2	1.23		1.32	0.048		0.052
C3	2.20		2.60	0.087		0.102
D	8.90		9.90	0.350		0.390
E	9.90		10.3	0.390		0.406
F	6.30		6.90	0.248		0.272
G		2.54			0.1	
H	28.0		29.8	1.102		1.173
L1		3.39			0.133	
L2	1.14		1.70	0.045		0.067
L3	2.65		2.95	0.104		0.116
Φ		3.6			0.142	

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